

Overview

The purpose of this notification is to communicate the addition of a Vacuum Formed Tray packing media for use with new pack multiple methodology for small quantity FCBGA, BGA and QFP shipments.

Description

In order to provide an optional packaging and shipping solution for partial tray shipments, Xilinx will be implementing a new pack multiple methodology for FCBGA, BGA and QFP package products. This new shipping multiple will be shipped in a new Vacuum Formed Tray media.

The new Vacuum Formed Tray is an ESD coated APET (Amorphous Polyethylene Terephthalate) material. This design will incorporate partial carrier tapes (65 mm, 44 mm, or 24 mm) as a device protector attached into the tray cavities for device packing and shipping protection. The Vacuum Formed Tray lid serves to hold down the device during shipping.

This Vacuum Formed Tray will include single and multiple packing capabilities, this will allow packing with a single unit or up to 5 units. Xilinx will not mix more than one device type within a same tray. In addition, mixing is not allowed between existing JEDEC trays and new Vacuum Formed Tray within the same shipment.

Reference Documents / Attachments:

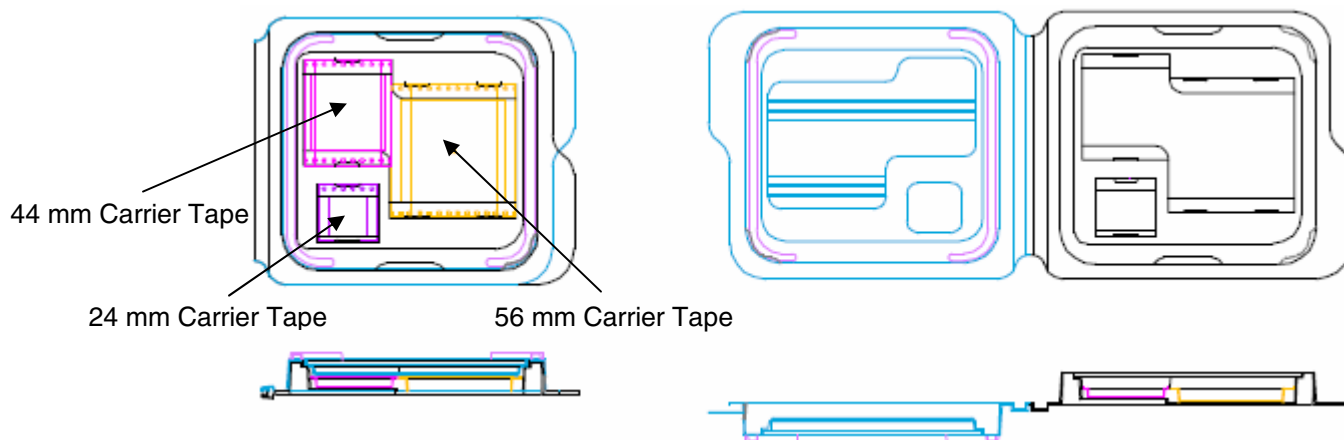


Figure 1 – Single Unit Vacuum Formed Tray

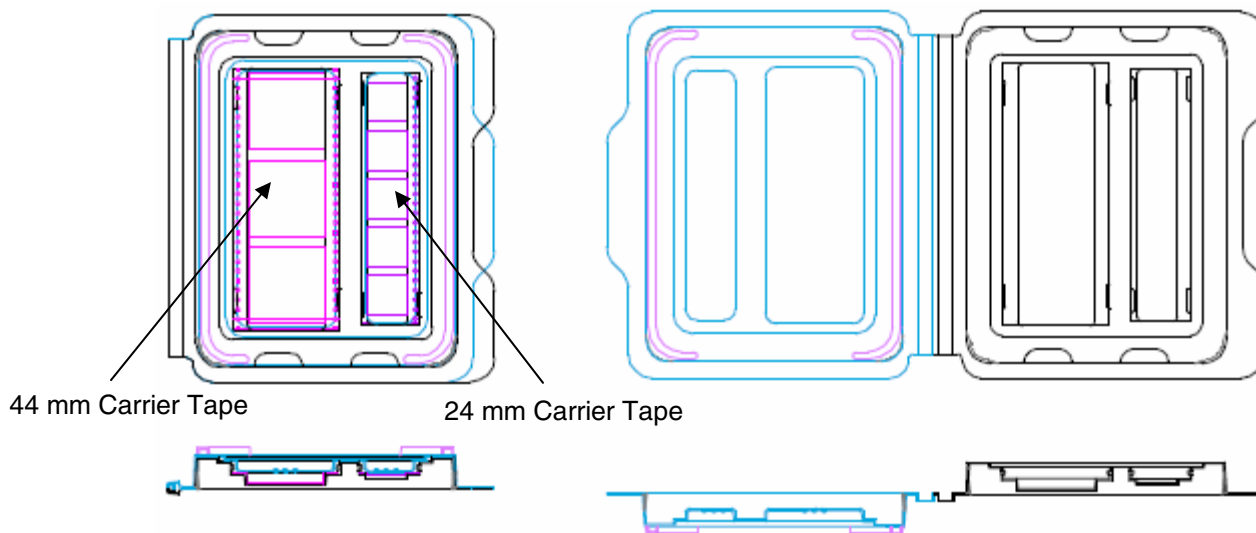


Figure 2 – Multiple Units Vacuum Formed Tray

Products Affected

All Xilinx BF/BFG, BG/BGG, CP/CPG, CS/CSG, EF/EFG, FF/FFG, FG/FGG, FT/FTG, FS/FSG, HT/HTG, HQ/HQG, MQ/MQG, QF/QFG, TQ/TQG, and VQ/VQG package products shipping in JEDEC trays with single or up to five (5) unit orders are affected by this notice.

Key Dates

Xilinx will begin using the new shipping multiples & Vacuum Formed Trays beginning August 15, 2008.

Recommendation

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

Important Notice: Xilinx Customer Notifications (PCN, PDN, and Quality Alerts) can be delivered via e-mail alerts sent by the MySupport website (<http://www.xilinx.com/support>). Register today and personalize your "MyAlerts" to include Customer Notifications. This change provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, and so forth. For instructions on how to sign up, refer to [Xilinx Answer Record 18683](#).

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
08/11/08	1.0	Initial Xilinx release.